

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JOHN E. MCCONNELL	08/01/2013
GARRY L. RENNER	08/01/2013
JOHN BULTITUDE	08/01/2013
ALLEN HILL	08/01/2013
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14925056
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<b>ATTORNEY DOCKET NUMBER:</b>	16066.CE.0311.3
<b>NAME OF SUBMITTER:</b>	JOSEPH T. GUY
<b>SIGNATURE:</b>	/Joseph T. Guy/
<b>DATE SIGNED:</b>	10/28/2015
<b>Total Attachments: 2</b>	
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**Assignment of Rights, Title and Interest in Invention  
(Multiple inventors; single assignee)**

**Docket No.  
16066.CE.0311**

*This is an Assignment of the follo wing rights, title and interest: (check all that apply):*

- United States of America rights, title and interest in the invention*
- Foreign rights, title and interest in the invention*
- United States Patent Application Serial No. \_\_\_\_\_*  
*Date of Execution: \_\_\_\_\_ Date of Filing: \_\_\_\_\_*
- United States Provisional Patent Application Serial No. \_\_\_\_\_*
- United States Patent No(s). \_\_\_\_\_*
- International (PCT) Patent Application Serial No. \_\_\_\_\_*
- Other (specify) \_\_\_\_\_*

*Title of the Invention*

**Leadless Multi-Layered Ceramic Capacitor Stacks**

*Inventors (assignors)*

<i>Name</i>	<i>Address</i>
<b>John E. McConnell</b>	<b>2835 Kemet Way, Simpsonville SC 29681</b>
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**Assignment of Rights, Title and Interest in Invention  
(Multiple inventors; single assignee)**

**Docket No.  
16066.CE.0311**

*Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention ");*

*And, whereas we desire to assign our above-identified rights, title and interest in the invention to the above-identified Assignee;*

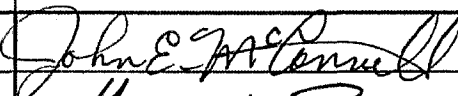
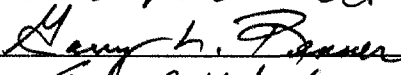

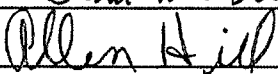
*Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged;*

*We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and an Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and an reissues and reexaminations thereof, and in and to any and an priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;*

*And we hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;*

*And we further agree to sign and execute an necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.*

**Inventors' Signatures**

Name	Signature / Date
John E. McConnell	 01-Aug-2013
Garry L. Renner	 01-Aug-2013
John Bultitude	 01-Aug-2013
Allen Hill	 01-Aug-2013